

# 300 Series IC Programmer

## 300 Series IC Programmer

- Support eMMC and UFS
- Excellent programming performance on high-density NAND Flash and eMMC



**ALL-300G2**  
Universal Gang Programmer



**UFS-300S**  
UFS Programmer (For UFS only)



**ALL-300S**  
Engineering Universal Programmer



- Palm size and space saving
- Best for engineering development and QC inspection

- Support up to 16 sockets
- Best for small to medium volume, high density device programming production

- Support UFS 2.0, UFS 2.1, UFS 3.0, and UFS 3.1
- Support MIPI M-PHY V3.0
- UniPro Specification V1.6
- UFS Card Extension V1.0
- Support up to 2 Lane Gear 3 (Rate A/ Rate B)
- Support 19.2MHz / 26MHz RCLK frequency
- Support UFS LUN read/write
- Support all settings such as Descriptor and Attributes
- 64G internal memory (expandable)
- Support USB 3.1 Gen1 (USB3.0) with download speed up to 280 MB/s

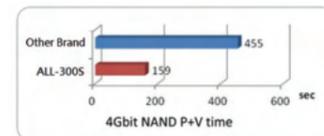
### Ultra high UFS programming speed

- Program speed up to 230 MB/s
- Verify speed up to 880 MB/s

Data size	Program	Verify
8G	43s	10s
16G	84s	19s

### High programming speed

Three times faster than competitors' programmer in the case of high-density NAND Flash and eMMC



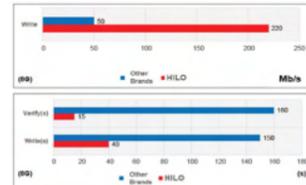
## ALL-300G2

- Support UFS device by only changing PACK
- High programming speed
- Expansion flexibility for production

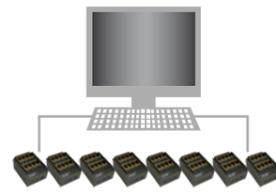
- Simplified and user-friendly design for users to operate
- Support UFS device simply by changing the PACK on the top of the BASE



- Three times faster than competitors' programmer in the case of high-density NAND Flash and eMMC
- Four times faster than competitors' programmer in the case of UFS device



- One computer can connect to 8 units of ALL-300G2 at the same time
- Up to 128 devices can be programmed simultaneously



## Feature

### Excellent programming performance

- Cutting-edge programming core delivers the fastest and most stable programming performance on high-density NAND Flash and eMMC
- Full IC pin contact check prevents bad contact in socket or IC damage from reversed placement

### High data transfer speed

- USB3.1 Gen 1 (USB3.0) transferring interface significantly increase the programming speed

### Support wide range of IC devices and packages

- Device supported: UFS, eMMC, eMCP, MCU/MPU, NOR/NAND Flash EEPROM, SPI Memory, FPGA, CPLD, etc.
- Package supported: DIP, SDIP, SOP, SSOP, TSOP, PLCC, QFP, QFN, SON, BGA, WLCSP, etc.



### Brand-new software interface

- Intuitive graphical user interface
- Clear display of each function in the entire programming procedure
- Display details and status of each device during programming



### Timely software support

- Fast software support by customer's request
- The supporting software is updated weekly on HI-LO website for checking or retrieving
- All programming problems will be followed and handled immediately

## Specification

	ALL-300S	UFS-300S	ALL-300G2
Device supported	eMMC, eMCP, MCU/MPU, NOR/NAND Flash EEPROM, SPI Memory, FPGA, CPLD, etc.	UFS	UFS, eMMC, eMCP, MCU/MPU, NOR/NAND Flash EEPROM, SPI Memory, FPGA, CPLD, etc.
Package supported	DIP, SDIP, SOP, SSOP, TSOP, PLCC, QFP, QFN, SON, BGA, WLCSP, etc.		
Support IC pin count	8 pins ~ 300 pins		
Socket number	1 socket	1 socket	Support up to 16 sockets
Key functions	Load File, Read Master, Program, Verify, Auto, ID Check, Checksum, Blank Check, Erase, Secure, Protect / Unprotect, Edit, Function Configuration, Self Test, etc.		
Data transfer interface	USB 2.0, USB 3.1 Gen1 (USB3.0)		
Compatible OS	Windows 7, 10		
Power	AC 100 - 240V / 50 - 60Hz		
Power consumption	60W	60W	150W
Operation temperature	0 ~ 40°C (32 ~ 105°F)		
Dimension	W140 x D181 x H45 (mm)	W140 x D181 x H42 (mm)	With PACK-ALL: W205 x D250 x H161 (mm) With PACK-UFS: W205 x D250 x H164 (mm)
Weight	1.12kg	1.08kg	3.5 kg